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PATENT

15868 U.S. PTO  
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Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

The patent application of

Inventor(s): AMAGAI ET AL

For: LEAD-FREE SOLDER ALLOY

is attached for filing.

[x] This application is being filed without a declaration or fee.

[x] This application claims the priority of:  
Japanese Patent Application No. 2002-199666 filed on  
July 9, 2002, and  
Japanese Patent Application No. 2002-217925 filed on  
July 26, 2002

Respectfully submitted,

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